

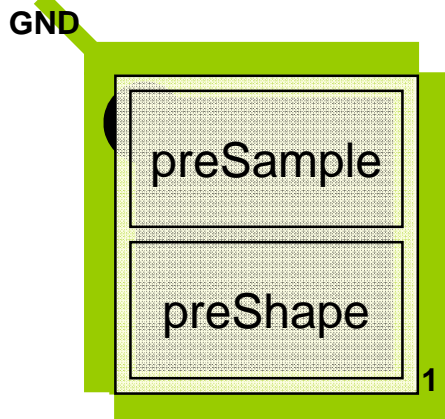
TPAC1 Thermal Images

Quick look: 28th November 2007

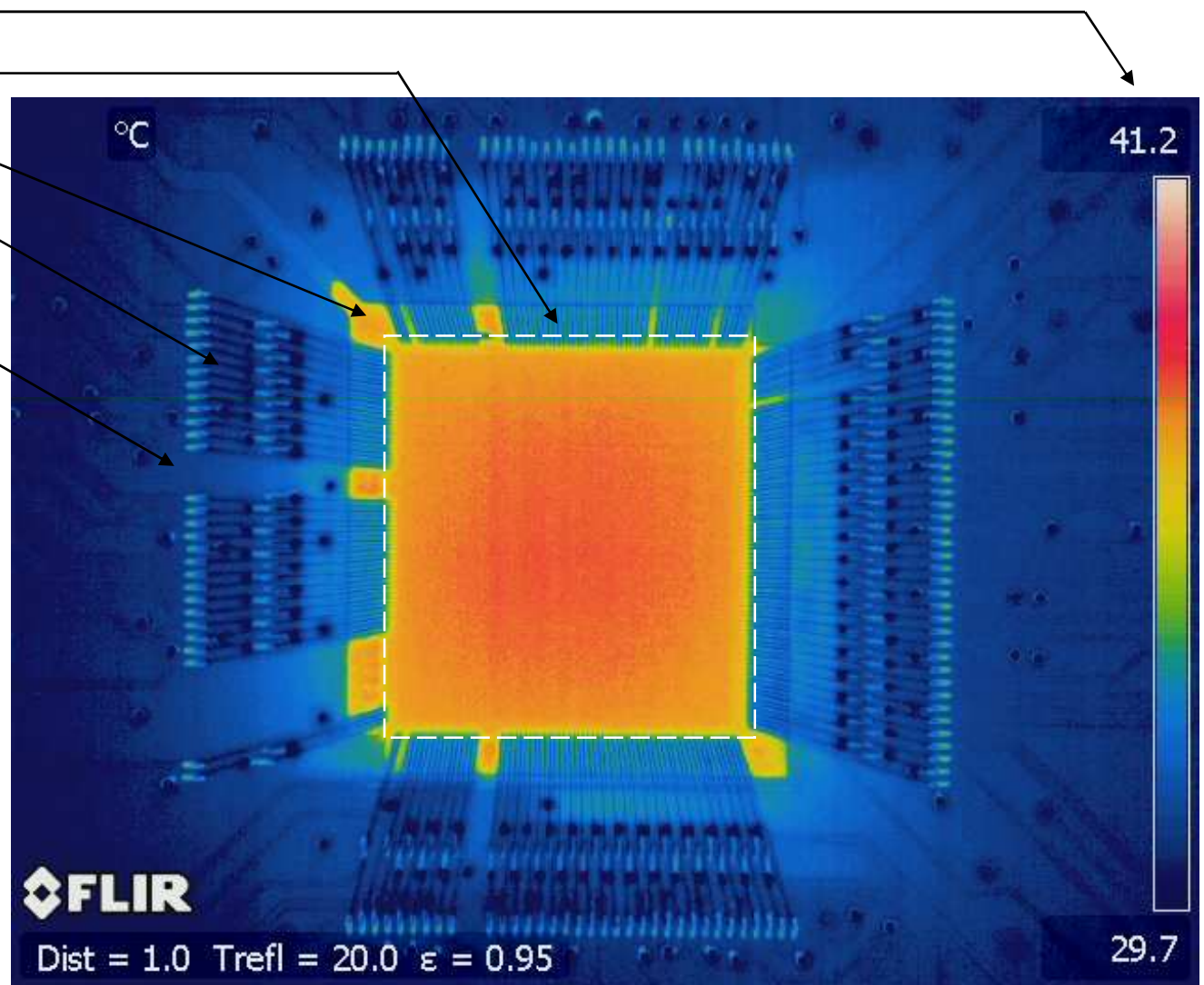
Orientation: Chip top view

- Temp scale
- Chip outline
- Ground pad
- Bond wires
- PCB

- Orientation

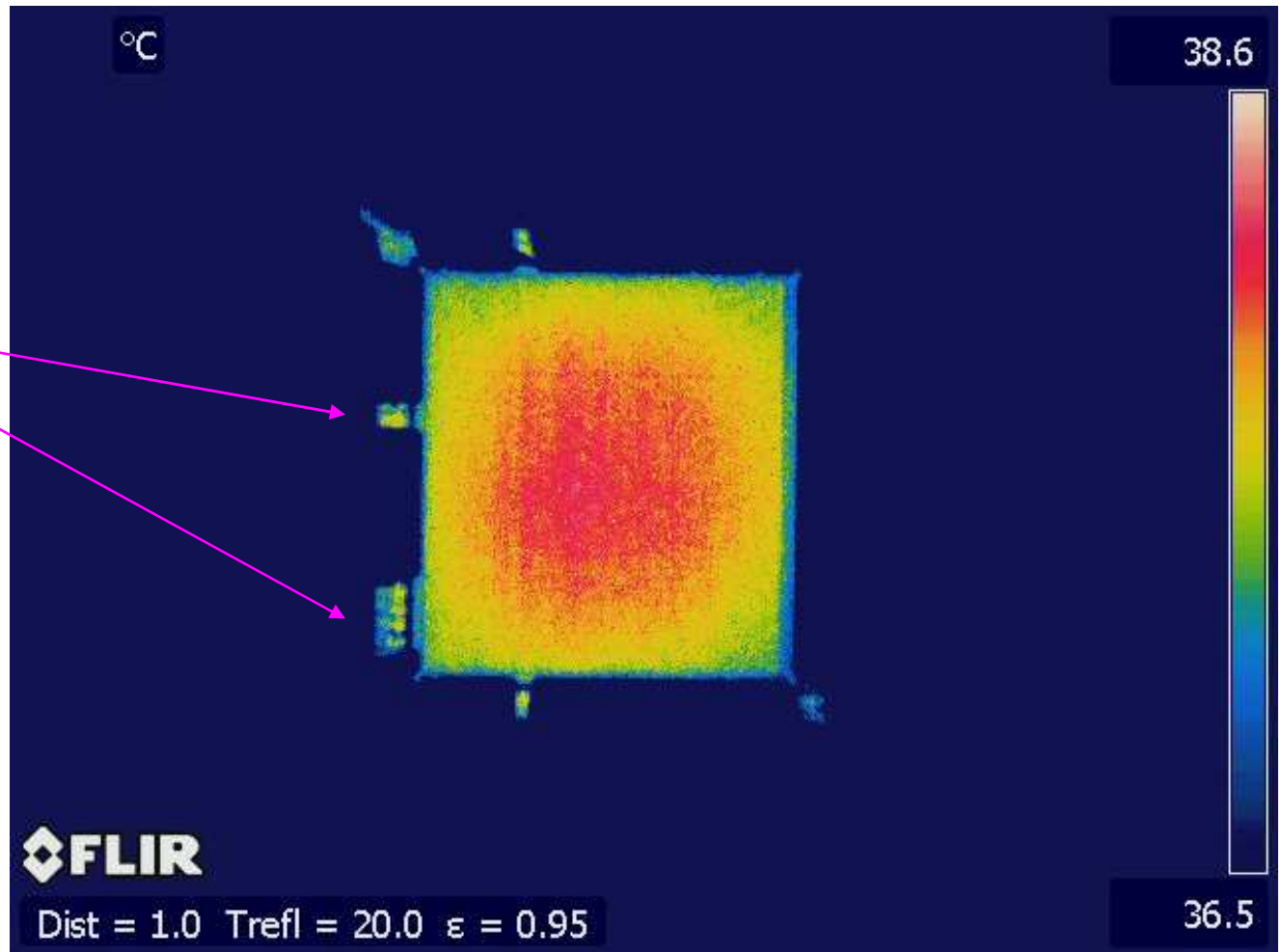


IR_0018.jpg



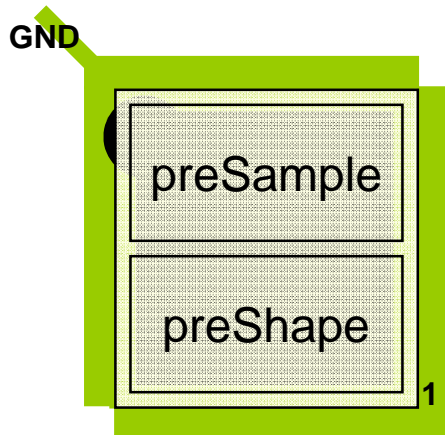
Bunch train operation: Fine temp range

- No obvious features in chip temp
- Gaps in bond wires showing ground pad beneath

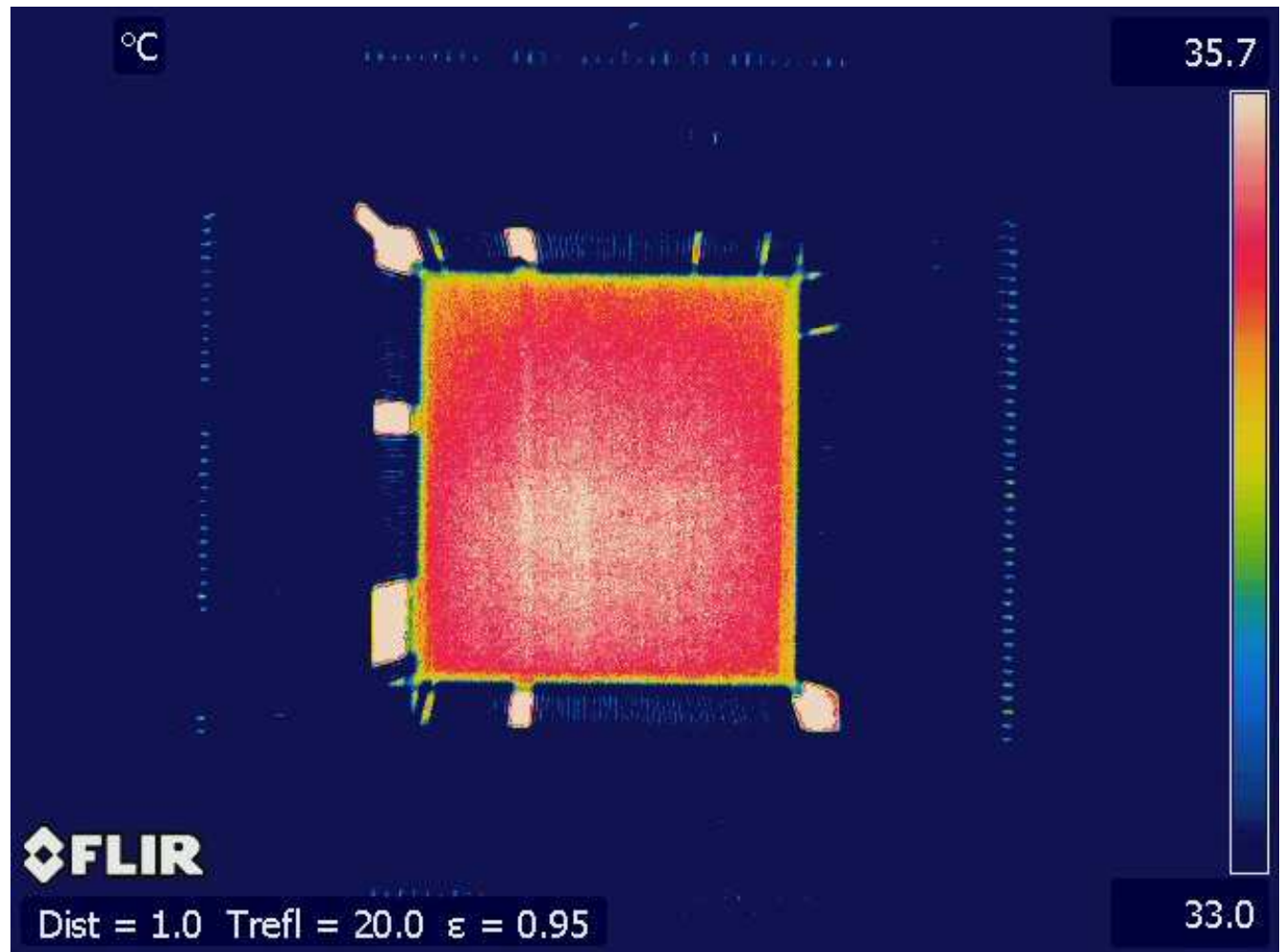


IR_0020.jpg

Idle: only preShape pixels enabled



IR_0023.jpg

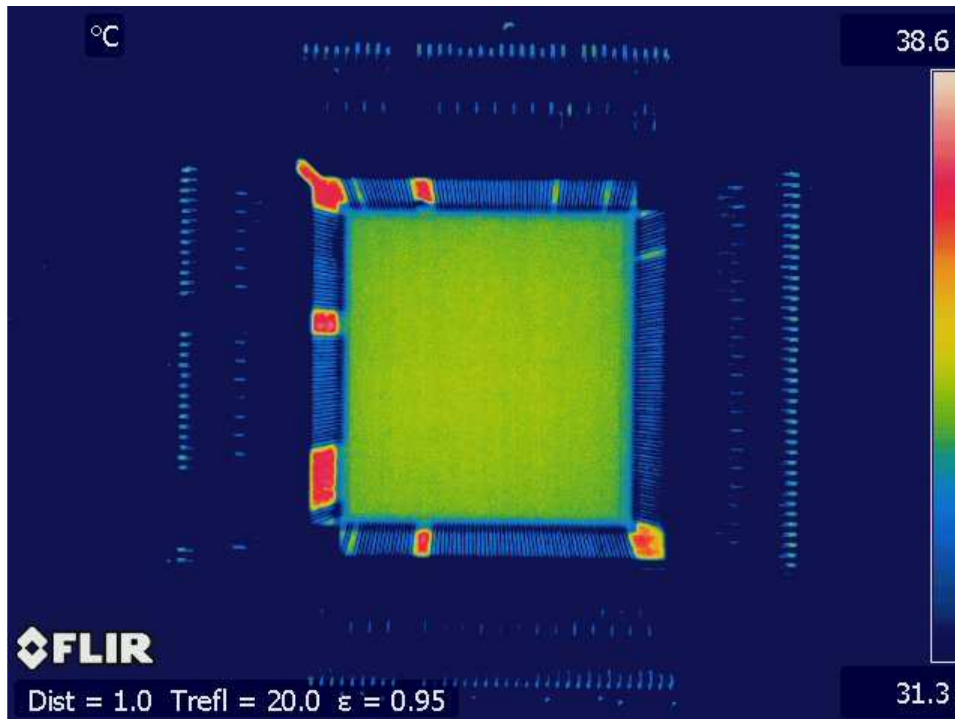


Idle: All pixels enabled/disabled

- Same temp scale used for both images

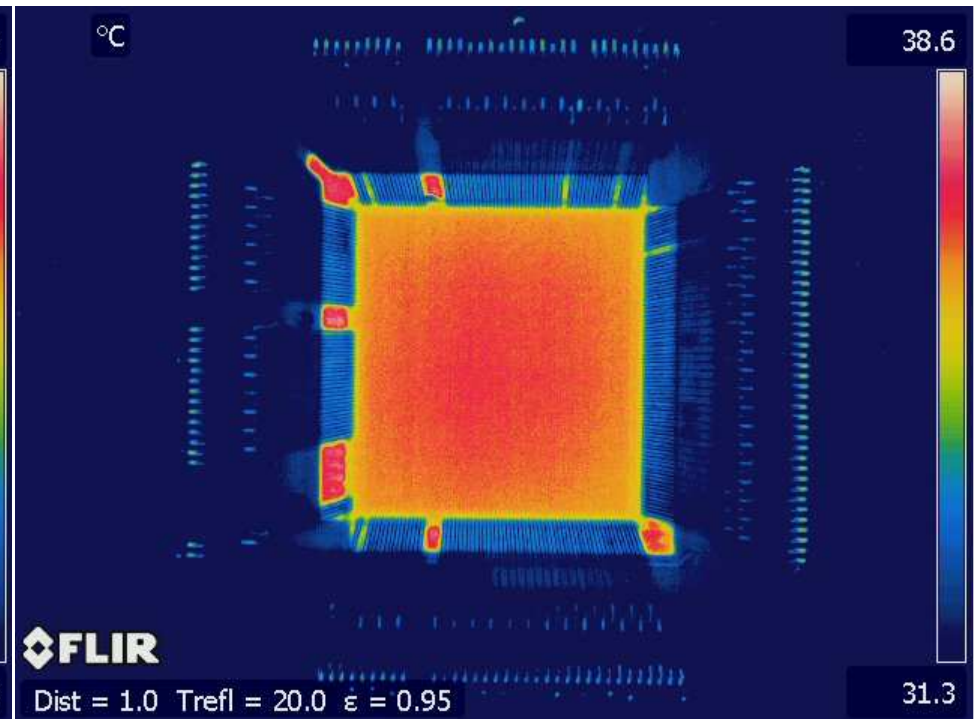
IR_0027.jpg

preShape and preSample disabled



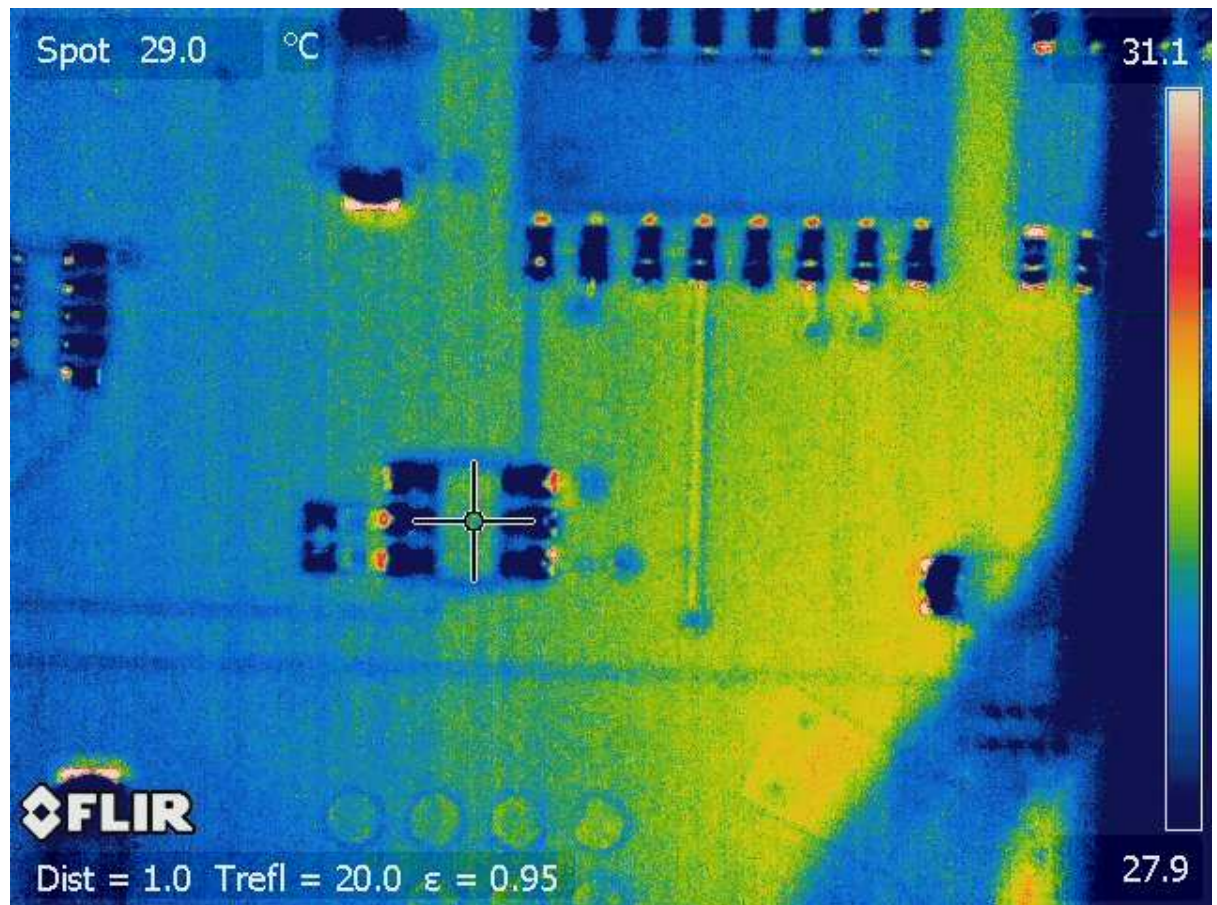
IR_0028.jpg

preShape and preSample enabled



Cross-check

- Temperature sensor on PCB
- Digital readback reports 27.5°C
- Camera reads 29°C



IR_0038.jpg